PI-2574 polyimide precursor

Product	PI-2574 polyimide precursor
Manufacturer	HD MicroSystems
Composition	10–30% polyamic acid of benzophenone tetracarboxylic dianhydride/4,4-oxydianiline/m-phenylenediamine polymer, >60% n-methyl pyrrolidone; liquid
Synonyms	Pyralin® polyimide precursor coatings
Typical Uses	Low-temperature spin-on polyimide
Hazards	201 Skin corrosion/irritation
Storage	Stock bottle to be stored in the resist fridge at the end of wet aisle 2. Working quantities may be poured into amber bottles and stored at room temperature in the solvent cabinet in wet aisle 2.
Disposal	Solid: Organic waste / organic sharps waste buckets under Aisle 1 fumehood. Liquid: solvent waste bottles in litho wet decks or wet decks 1A/1B/2A.
Comments	To be spun onto substrates, followed by a soft bake on a hotplate. Must be spun using the Headway Spinner, with a foil-lined bowl, in the Aisle 1 fumehood. Softbake on a hotplate in this fumehood. Curing allowed in Bottom Minibrute furnace.
Status	



Check First

Please contact a nanoFAB staff member for uses not listed above.